



PATENT APPLICATION

IN THE U.S. PATENT AND TRADEMARK OFFICE

April 5, 2010

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION

Serial No.: 10/576 231 Group: 1792

Confirmation No.: 7188

Filed: April 14, 2006 Examiner: Bareford

International Application No.: PCT/JP2004/011327

International Filing Date: July 30, 2004

Atty. Docket No.: 4700.P0327US

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

LETTER TO EXAMINER

Sir:

This Request for Continued Examination is being filed in order to have the Amendment After Final Rejection dated March 4, 2010 entered into the record of the present application. As discussed in the last Response, the instant invention provides the addition of a water-soluble nitrogen-containing polymer to an electroless copper plating solution containing phosphinic acid and glyoxylic acid as reducing agents to improve the initial plating reactivity through the catalyst metal and thereby enable the provision of uniform plating at a lower temperature on a semiconductor or other mirrored-surface substrate. This allows the plating deposition speed to be controlled, the crystals to become finer and the adhesion of the plating to a wafer or other mirrored-surface substrate to increase. It is respectfully submitted that the prior art cited by the Examiner does not

disclose the presently claimed invention. Favorable consideration is respectfully solicited.

Respectfully submitted,


Terryence F. Chapman

TFC/smd

FLYNN, THIEL, BOUTELL
& TANIS, P.C.
2026 Rambling Road
Kalamazoo, MI 49008-1631
Phone: (269) 381-1156
Fax: (269) 381-5465

Terryence F. Chapman	Reg. No. 32 549
Mark L. Maki	Reg. No. 36 589
Liane L. Churney	Reg. No. 40 694
Brian R. Tumm	Reg. No. 36 328
Heon Jekal	Reg. No. 64 219
Eugene J. Rath III	Reg. No. 42 094
Dale H. Thiel	Reg. No. 24 323
David G. Boutell	Reg. No. 25 072
Sidney B. Williams, Jr.	Reg. No. 24 949

Encl: None

110.10/07